



# APPROVAL SHEET

| Approval Specification      | Customer's Approval Certificate                             |
|-----------------------------|---|
| <b>TO:</b>                  | Please return this copy as a certification of your approval |
| <b>Part No.:</b>            | <b>Checked &amp; Approved by:</b>                           |
| <b>Customer's Part No.:</b> | <b>Date:</b>  |

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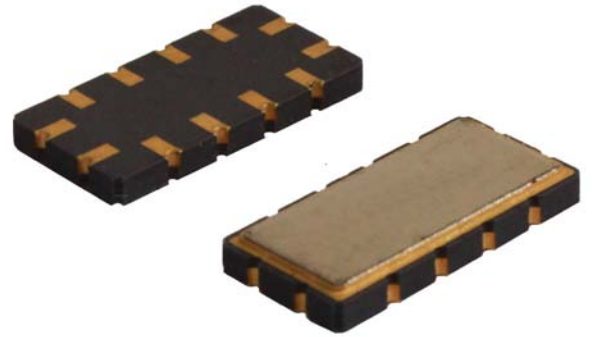


|          |   |          |
|----------|---|----------|
| Part No. | : | SF1624   |
| Pages    | : | 6        |
| Date     | : | 2017/1/3 |
| Revision | : | 1.0      |

|                     |     |
|---------------------|-----|
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| <b>Approved by:</b> | 卢翠  |

**Application**

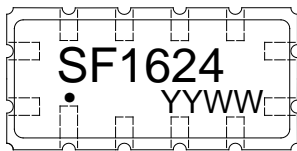
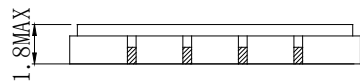
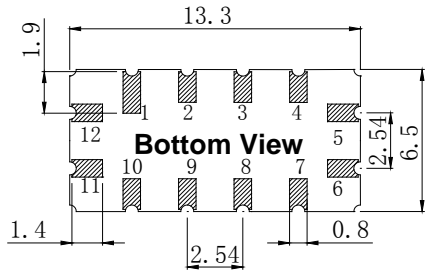
- High-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable Passband 28.0 MHz



**Features**

- Ceramic Package for **Surface Mounted Technology (SMT)**
- **RoHS** compatible
- Package size 13.30x6.50x1.80mm<sup>3</sup>
- Package Code QCC12
- **Electrostatic Sensitive Device(ESD)**

**Package Dimensions (Unit: mm)**



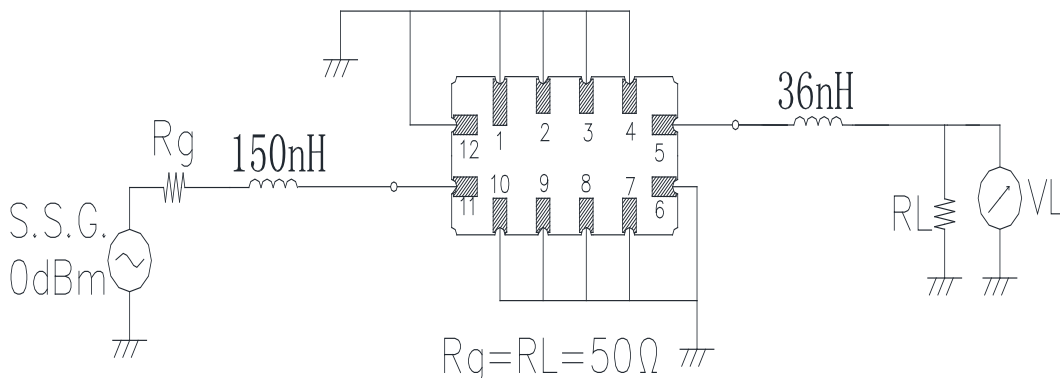
**Pin Configuration**

| Pin No.               | Description |
|-----------------------|-------------|
| 11                    | Input       |
| 5                     | Output      |
| 1,2,3,4,6,7,8,9,10,12 | Ground      |

**Marking Description**

|             |                       |
|-------------|-----------------------|
| <b>S</b>    | Trademark             |
| <b>F</b>    | SAW Filter            |
| <b>1624</b> | Part Number           |
| ●           | Pin 1                 |
| <b>YYWW</b> | Year Code & Week Code |

**Test Circuit(Bottom View)**



\*Fig: If the products produced in 06<sup>th</sup> week of 2012, The year code & week code is 1206.

**Performance****Maximum Rating**

| Item                  |           | Value      | Unit |
|-----------------------|-----------|------------|------|
| DC Voltage            | $V_{DC}$  | 3          | V    |
| Operation Temperature | T         | -55 ~ +85  | °C   |
| Storage Temperature   | $T_{stg}$ | -55 ~ +125 | °C   |
| RF Power Dissipation  | P         | 10         | dBm  |

**Electronic Characteristics**

Test Temperature:  $25^{\circ}\text{C} \pm 2^{\circ}\text{C}$

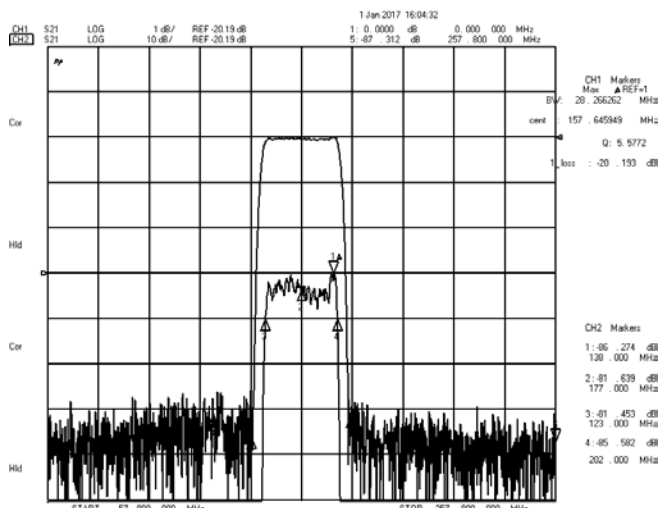
Terminating source impedance:  $50\Omega$

Terminating load impedance:  $50\Omega$

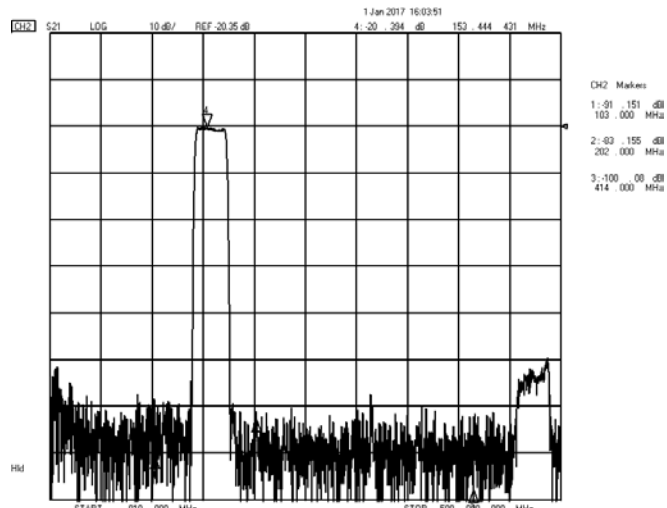
| Item                   |                | Minimum | Typical | Maximum | Unit |
|------------------------|----------------|---------|---------|---------|------|
| Center Frequency       | $f_c$          |         | 157.80  |         | MHz  |
| Insertion Loss(min)    | IL             |         | 20.2    | 22.0    | dB   |
| Amplitude Ripple (p-p) | $\Delta\alpha$ |         | 0.7     | 1.0     | dB   |
| 1 dB Bandwidth         | $BW_{1dB}$     |         | 28.0    |         | MHz  |
| Absolute Delay@Fc      | AD             |         | 0.9     |         | us   |
| Absolute Attenuation   | $\alpha$       |         |         |         |      |
| DC-103.00MHz           |                | 40      | 45      |         | dB   |
| 103.00-123.00MHz       |                | 50      | 55      |         | dB   |
| 133.00-138.00MHz       |                | 30      | 35      |         | dB   |
| 177.00-182.00MHz       |                | 30      | 35      |         | dB   |
| 182.00-202.00MHz       |                | 50      | 55      |         | dB   |
| 202.00-414.00MHz       |                | 40      | 45      |         | dB   |

Frequency Characteristics

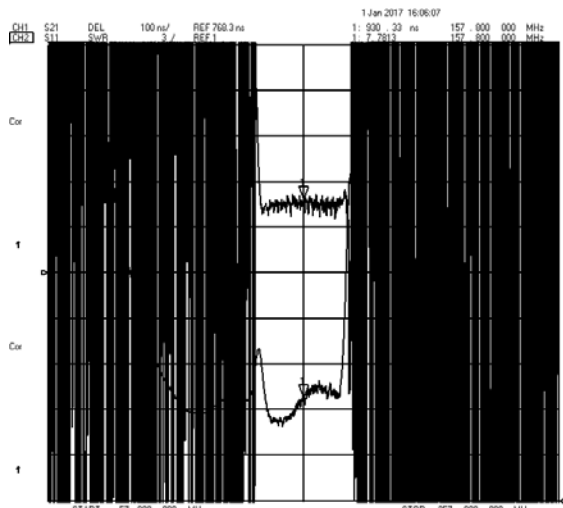
Frequency Response



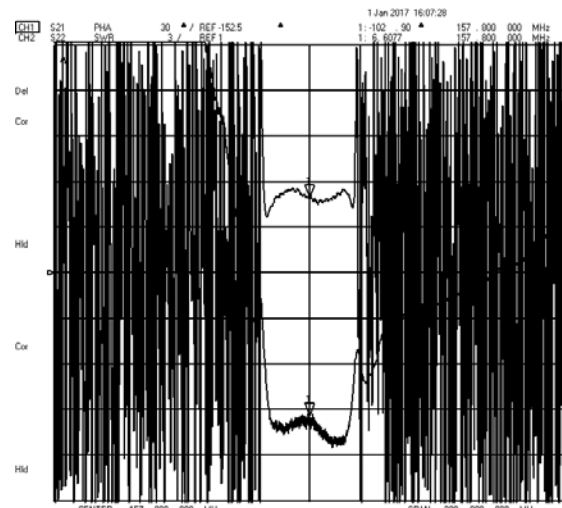
Frequency Response (wideband)



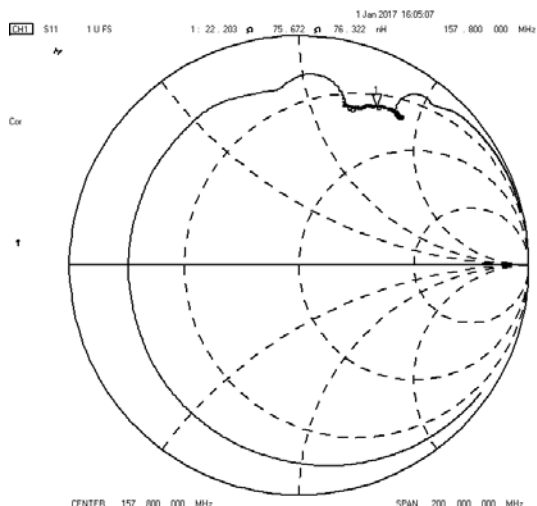
Delay Ripple & S11 VSWR



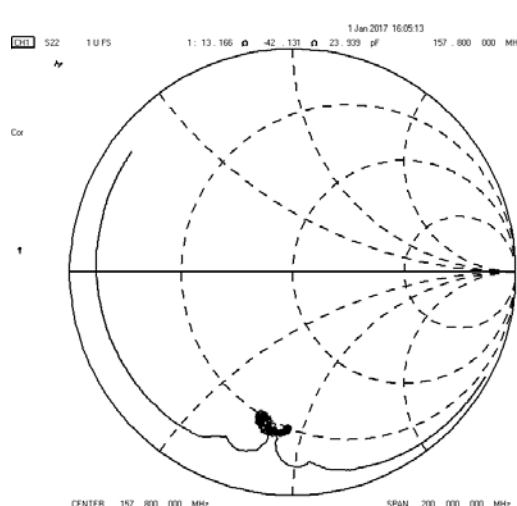
Phase Linearity & S22 VSWR



S11 Smith Chart



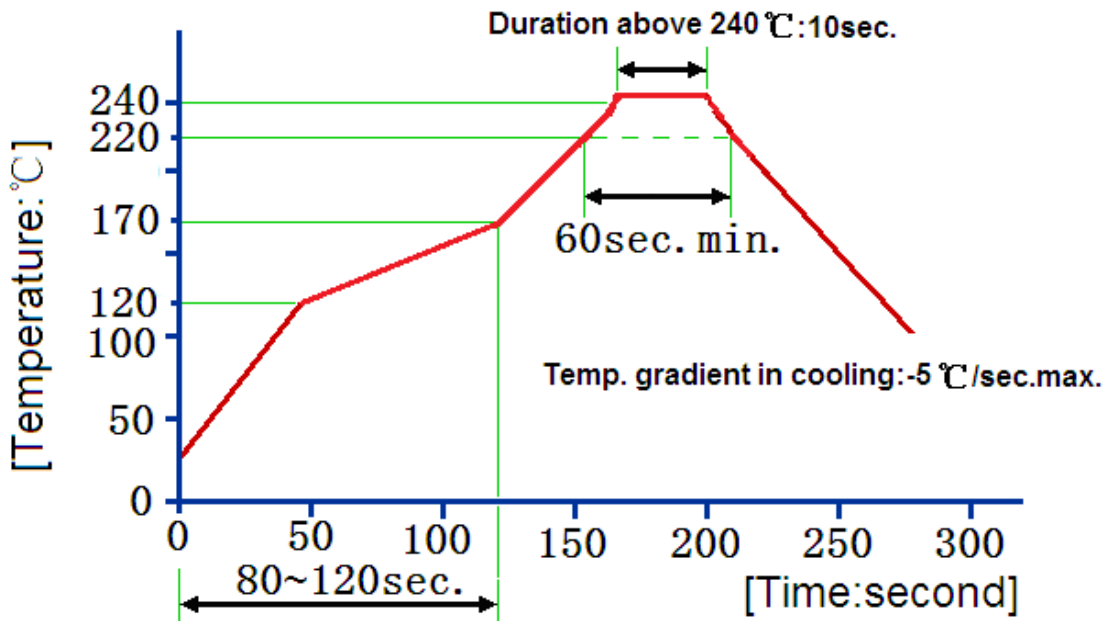
S22 Smith Chart



**Reliability (The SAW components shall remain electrical performance after tests)**

| No. | Test item                    | Test condition   |
|-----|------------------------------|--|
| 1   | Temperature Storage          | (1) Temperature: $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$ , Duration: 250h, Recovery time: $2\text{h} \pm 0.5\text{h}$<br>(2) Temperature: $-55^{\circ}\text{C} \pm 3^{\circ}\text{C}$ , Duration: 250h, Recovery time: $2\text{h} \pm 0.5\text{h}$      |
| 2   | Humidity Test                | Conditions: $60^{\circ}\text{C} \pm 2^{\circ}\text{C}$ , 90~95% RH                                  Duration: 250h   |
| 3   | Thermal Shock                | Heat cycle conditions: TA= $-55^{\circ}\text{C} \pm 3^{\circ}\text{C}$ , TB= $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$ , t1=t2=30min, Switch time: $\leq 3\text{min}$ , Cycle time: 100 times, Recovery time: $2\text{h} \pm 0.5\text{h}$ .               |
| 4   | Vibration Fatigue            | Frequency of vibration: 10~55Hz                                  Amplitude: 1.5mm<br>Directions: X, Y and Z    Duration: 2h  |
| 5   | Drop Test                    | Cycle time: 10 times    Height: 1.0m   |
| 6   | Solder Ability Test          | Temperature: $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ Duration: 3.0s--5.0s<br>Depth: DIP--2/3, SMD--1/5   |
| 7   | Resistance to Soldering Heat | (1) Thickness of PCB: 1mm, Solder condition: $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ , Duration: $10 \pm s$<br>(2) Temperature of Soldering Iron: $350^{\circ}\text{C} \pm 0^{\circ}\text{C}$ , Duration: 3~4s,<br>Recovery time : $2 \pm 0.5\text{h}$ |

**Recommended Reflow Soldering Diagram**



**Reflow cycles: 3 cycles max.**

**Notes**

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.